

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-15. (Canceled)

16. (Currently amended) A cover for a semiconductor device having a substrate with an optical unit formed thereon, the cover comprising:

a portion defining a first opening on a surface of the cover;

a portion defining a second opening on the surface of the cover; and

a portion defining a third opening on the surface of the cover, wherein the first opening is formed between the second opening and the third opening; and

a translucent portion in at least the portion defining the second opening, wherein the first opening is formed along a circumference of the second opening, and wherein the first opening contains an adhesive for affixing the cover to the substrate, and wherein the second opening is formed to receive and surround the optical unit inside of the second opening when the cover is affixed to the substrate, and wherein the second opening that includes the optical unit is sealed from the adhesive in the first opening.

17-19. (Canceled)

20. (Currently amended) ~~The~~ A cover for ~~the~~ a semiconductor device ~~according to claim 16, further~~ having a substrate with an optical unit formed thereon, the cover comprising:

a portion defining a first opening on a surface of the cover;

a portion defining a second opening on the surface of the cover;

a translucent portion in at least the portion defining the second opening, wherein the first opening is formed along a circumference of the second opening, and wherein the first opening contains an adhesive for affixing the cover to the substrate, and wherein the second opening is formed to receive and surround the optical unit inside of the second opening when the cover is affixed to the substrate.

and wherein the second opening that includes the optical unit is sealed from the adhesive in the first opening; and

a portion defining a through-hole that extends from a back side of the surface that includes the portion defining the first opening to inside the first opening.

21. (Previously presented) The cover for the semiconductor device according to claim 20, further comprising:

a portion that is formed in line along the cover; and

a slit that is formed in line on the portion of the first opening that is formed in line.

22. (Currently amended) The A cover for the a semiconductor device ~~according to claim 16,~~ having a substrate with an optical unit formed thereon, the cover comprising:

a portion defining a first opening on a surface of the cover;

a portion defining a second opening on the surface of the cover; and

a translucent portion in at least the portion defining the second opening,

wherein the first opening is formed along a circumference of the second opening, and wherein the first opening contains an adhesive for affixing the cover to the substrate, and wherein the second opening is formed to receive and surround the optical unit inside of the second opening when the cover is affixed to the substrate, and wherein the second opening that includes the optical unit is sealed from the adhesive in the first opening;

wherein the first opening is formed so as to penetrate from one side of the cover to the other side of the cover.

23. (Canceled)